Concentration of the AI Chip Supply Chain

Expressed as percentage of total market share

Design of AI Chips

Data: 2023.

OTHERS (MOSTLY INTEL & AMD) • 5-20% **NVIDIA** 80-95%

This excludes AI chips that are not available to purchase, for instance AI chips that are only available "to rent", such as Google's TPUs. Information on the production volume and revenue of such custom chips is limited. However, we estimate that Google's TPUs could make up a significant minority of all AI chips.

Semiconductor Manufacturing Equipment

An input to fabrication. Data: 2023. Extreme Ultraviolet Lithography (EUV).

ASML 100%

ASML is the only company capable of producing EUV machines. These machines are critical to produce <5 nm chips and to produce 5 nm chips economically (Grunewald, 2023). In 2023, they were also used to produce almost all 7 nm chips, with the exception of Chinese manufacturer SMIC who in 2023 began producing 7nm chips with inferior DUV equipment due to export restrictions on EUV (Schleich and Reinsch, 2023).

Fabrication

Data: 2022. Logic chips ≤7nm.

SAMSUNG & INTEL • 10%

TSMC 90%

Compute Provision

Data: 2023.

OTHERS • 35%

GOOGLE CLOUD • 11%

MICROSOFT AZURE • 22%

Amazon Web Services 32%

It is ambiguous whether market share figures
exclusively cover the pure-play foundry market, i.e.,
manufacturing capacity dedicated to serving
external customers, or if it also includes capacity for

This covers the entire cloud market and is not
specific to AI compute. However, we expect that
these three companies have a similar, or even
bigger, market share in the AI cloud compute sector.

exclusively cover the pure-play foundry market, i.e., manufacturing capacity dedicated to serving external customers, or if it also includes capacity for chips that are used for their own products. However, even when accounting for this, TSMC would likely still dominate the market by a large

margin, and the production is still limited to a small

number of actors.

"Computing Power and the Governance of Artificial Intelligence" Sastry, Heim, Belfield, Anderljung, Brundage, Hazell, O'Keefe, Hadfield et al., 2024